

16. Deep Submicron (DSM) Issues

- Last module:
 - Pass transistor logic
 - Pseudo nMOS logic
 - Dynamic logic
 - Domino circuits
- This module
 - Transistor I-V Review
 - Nonideal Transistor Behavior
 - Process and Environmental Variations

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Ideal Transistor I-V

- Shockley 1st order transistor models

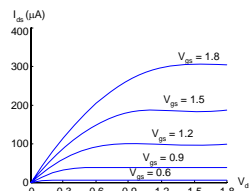
$$I_{ds} = \begin{cases} 0 & V_{gs} < V_t & \text{cutoff} \\ \beta \left(V_{gs} - V_t - \frac{V_{ds}}{2} \right) V_{ds} & V_{ds} < V_{dsat} & \text{linear} \\ \frac{\beta}{2} (V_{gs} - V_t)^2 & V_{ds} > V_{dsat} & \text{saturation} \end{cases}$$

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Ideal nMOS I-V Plot

- 180 nm TSMC process
- Ideal Models
 - $\beta = 155(W/L) \mu A/V^2$
 - $V_t = 0.4 V$
 - $V_{DD} = 1.8 V$

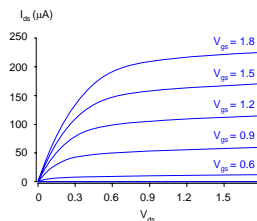


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Simulated nMOS I-V Plot

- 180 nm TSMC process
- BSIM 3v3 SPICE models
- What differs?
 - Less ON current
 - No square law
 - Current increases in saturation



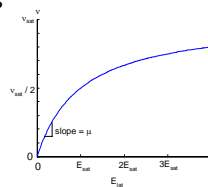
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Velocity Saturation

- We assumed carrier velocity \propto E-field
 - $v = \mu E_{lat} = \mu V_{ds}/L$
- At high fields, this ceases to be true
 - Carriers scatter off atoms
 - Velocity reaches v_{sat}
 - Electrons: $6-10 \times 10^6$ cm/s
 - Holes: $4-8 \times 10^6$ cm/s
 - Better model

$$v = \frac{\mu E_{lat}}{1 + \frac{E_{lat}}{E_{sat}}} \Rightarrow v_{sat} = \mu E_{sat}$$



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Velocity Saturation I-V Effects

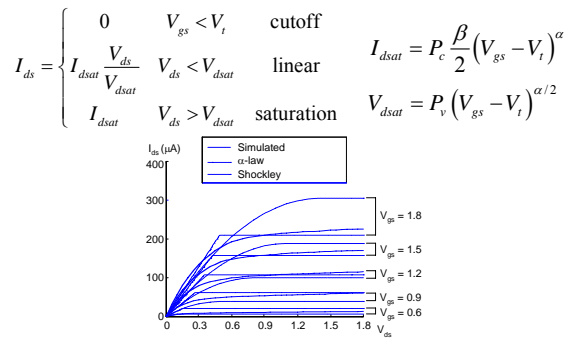
- Ideal transistor ON current increases with V_{DD}^2

$$I_{ds} = \mu C_{ox} \frac{W}{L} \frac{(V_{gs} - V_t)^2}{2} = \frac{\beta}{2} (V_{gs} - V_t)^2$$
- Velocity-saturated ON current increases with V_{DD}

$$I_{ds} = C_{ox} W (V_{gs} - V_t) v_{max}$$
- Real transistors are partially velocity saturated
 - Approximate with α -power law model
 - $I_{ds} \propto V_{DD}^\alpha$
 - $1 < \alpha < 2$ determined empirically

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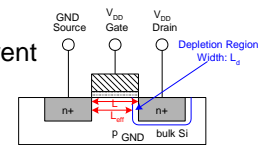
α -Power Model

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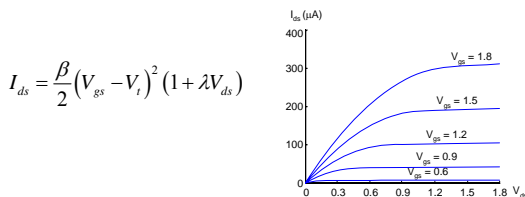
Channel Length Modulation

- Reverse-biased p-n junctions form a **depletion region**
 - Region between n and p with no carriers
 - Width of depletion L_d region grows with reverse bias
 - $L_{eff} = L - L_d$
- Shorter L_{eff} = more current
 - I_{ds} increases with V_{ds}
 - Even in saturation



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Channel Length Modulation I-V

- λ = *channel length modulation coefficient*
- not feature size
 - Empirically fit to I-V characteristics

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Body Effect

- Body is an implicit fourth terminal
- V_t : gate voltage necessary to invert channel
- The potential difference V_{sb} between the source and body affects V_t
- Increase in V_t with V_{sb} is called the *body effect*
- Body bias is a post-silicon tuning technique

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Body Effect Model

$$V_t = V_{t0} + \gamma (\sqrt{\phi_s + V_{sb}} - \sqrt{\phi_s})$$

- ϕ_s = *surface potential at threshold*
- $$\phi_s = 2v_T \ln \frac{N_A}{n_i}$$
- Depends on doping level N_A
 - And intrinsic carrier concentration n_i

- γ = *body effect coefficient*

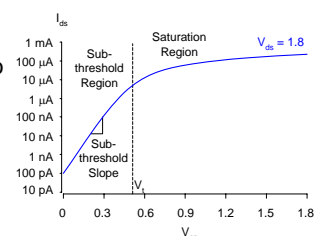
$$\gamma = \frac{t_{ox}}{\epsilon_{ox}} \sqrt{2q\epsilon_{si}N_A} = \frac{\sqrt{2q\epsilon_{si}N_A}}{C_{ox}}$$

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OFF Transistor Behavior

- What about current in cutoff?
- Simulated results
- What differs?
 - Current doesn't go to 0 in cutoff



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Leakage Sources

- Subthreshold conduction
 - Transistors can't abruptly turn ON or OFF
- Junction leakage
 - Reverse-biased PN junction diode current
- Gate leakage
 - Tunneling through ultra-thin gate dielectric
- Subthreshold leakage is the biggest source in modern transistors

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Subthreshold Leakage

- Subthreshold leakage exponential with V_{gs}

$$I_{ds} = I_{ds0} e^{\frac{V_{gs} - V_t}{nV_T}} \left(1 - e^{-\frac{V_{ds}}{V_T}} \right) \quad I_{ds0} = \beta V_T^2 e^{1.8}$$

- n is process dependent, typically 1.4-1.5

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DIBL

- Drain-Induced Barrier Lowering
 - Drain voltage also affect V_t
- $$V_t' = V_t - \eta V_{ds}$$
- High drain voltage causes subthreshold leakage to **increase**
 - Effect is especially pronounced in short-channel transistors

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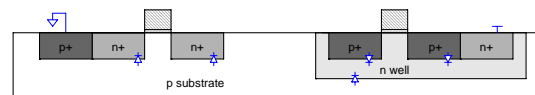
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Junction Leakage

- Reverse-biased p-n junctions have some leakage

$$I_D = I_S \left(e^{\frac{V_D}{V_T}} - 1 \right)$$

- I_S depends on doping levels
 - And area and perimeter of diffusion regions
 - Typically $< 1 \text{ fA}/\mu\text{m}^2$

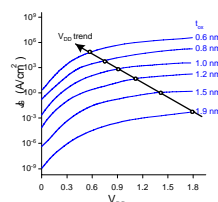


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Gate Tunneling Leakage

- Carriers may tunnel through very thin gate oxides
- Predicted tunneling current (from [Song01])



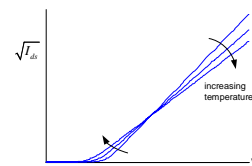
- Negligible for older processes
- May soon be critically important
 - Intel/IBM high-K dielectric material news 02/07

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Temperature Sensitivity

- Increasing temperature
 - Reduces mobility
 - Reduces V_t
- I_{ON} **decreases** with temperature
- I_{OFF} **increases** with temperature



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So What?

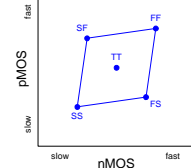
- So what if transistors are not ideal?
 - They still behave like switches.
- But these effects matter for...
 - Supply voltage choice
 - Logical effort
 - Quiescent/leakage power consumption
 - Pass transistors
 - Temperature of operation

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Parameter Variation

- Transistors have uncertainty in parameters
 - Process: L_{eff} , V_t , t_{ox} of nMOS and pMOS
 - Vary around typical (T) values
- Fast (F)
 - L_{eff} : short
 - V_t : low
 - t_{ox} : thin
- Slow (S): opposite
- Not all parameters are independent for nMOS and pMOS



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Environmental Variation

- V_{DD} and Temp also vary in time and space
- Fast:
 - V_{DD} : high
 - Temp: low

Corner	Voltage	Temperature
F (fast)	1.98	0 C
T (typical)	1.8	70 C
S (slow)	1.62	125 C

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Process Corners

- Process corners describe worst case variations
 - If a design works in all corners, it will probably work for any variation.
- Describe corner with letters (T, F, S)
 - nMOS speed
 - pMOS speed
 - Voltage
 - Temperature

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Important Corners

- Some critical simulation corners include

Purpose	nMOS	pMOS	V_{DD}	Temp
Cycle time	S	S	S	S
Power	F	F	F	F
Subthreshold leakage	F	F	F	S
Pseudo-nMOS	S	F	?	?

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